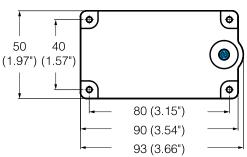
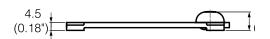


Item No. 53263

Ex SupraPlate, SupraX-263







mm (inch) weight: 44g (1.55oz)





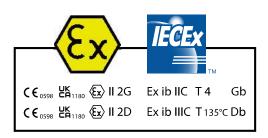
Features:

- By using the Supra Digital Chips with a third-party asset management application to achieve product traceability, manufacturer authentication and digitized product information.
- NFC enabled mobile device or smart phone (iOS 14 or greater required/ Android 12 or greater required) can be used as reader.
- Unique design of proprietary wafer-antenna chip construction.

Functionality	
RF Protocol	ISO 15693
Operating Frequency	HF - 13.56 MHz
Memory Configuration	UID 16 bits, User 2K bits
R/W Capability	Read / Write
Performance	
Read Range	Maximum to 5 mm (0.2")
Quality Guarantee	100 %
Orientation	Front Face Read
Physical	
Materials	Aluminum (Anodizing)
Mounting System	Universal Use
Operational	
Max Temperature Exposure	125 °C / 257 °F
Min Temperature Exposure	-30 °C / -22 °F
Continuous Max Service Temperature	125 °C / 257 °F
Continuous Min Service Temperature	-30 °C / -22 °F
Water and Ice Proof	Yes

Application:

Engineering Equipment, Machine











Patent Number

» Taiwan Patent: M573545

» China Patent: ZL 201821589819.6

» Japan Patent: 3219858» United States Patent: 10607128

» German Patent: 602018032891.2
» Italy Patent: 3627396
» UK Patent: 3627396

» Taiwan Patent: 1638765

» China Patent: ZL 2017 1 0821524.0

» United States Patent: 10235617

» United States Patent: 11305844» Japan Patent: 3220091